



Material Content Data Sheet



Sales Product Name		TLE8457CSJ		Issued		3. July 2019		
MA#		MA002422476						
Package		PG-DSO-8-44		Weight*		82.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	1.48	1.48	14759	14759
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8669	
wire	non noble metal	copper	7440-50-8	29.121	35.20	36.12	351995	361205
	non noble metal	copper	7440-50-8	0.077	0.09	0.09	930	930
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1201
encapsulation	plastics	epoxy resin	-	4.569	5.52		55225	
	inorganic material	silicondioxide	60676-86-0	44.993	54.39	60.03	543848	600274
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9837	9837
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7860	7860
glue	plastics	acrylic resin	-	0.093	0.11		1130	
	noble metal	silver	7440-22-4	0.331	0.40	0.51	4005	5135
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com